

# Samsung Flash Design Team Invited Seminar

Jun 27, 2024

## Industrial AI & its applications in manufacturing

**Sunghee Yun**

Co-founder - AI Technology & Product Strategy @ Erudio Bio, Inc.

# Today

1 why Industrial AI?

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2 computer vision ML in manufacturing

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3 time-series ML in manufacturing

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4 AI challenges for manufacturing

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5 Virtual Metrology - manufacturing AI success story

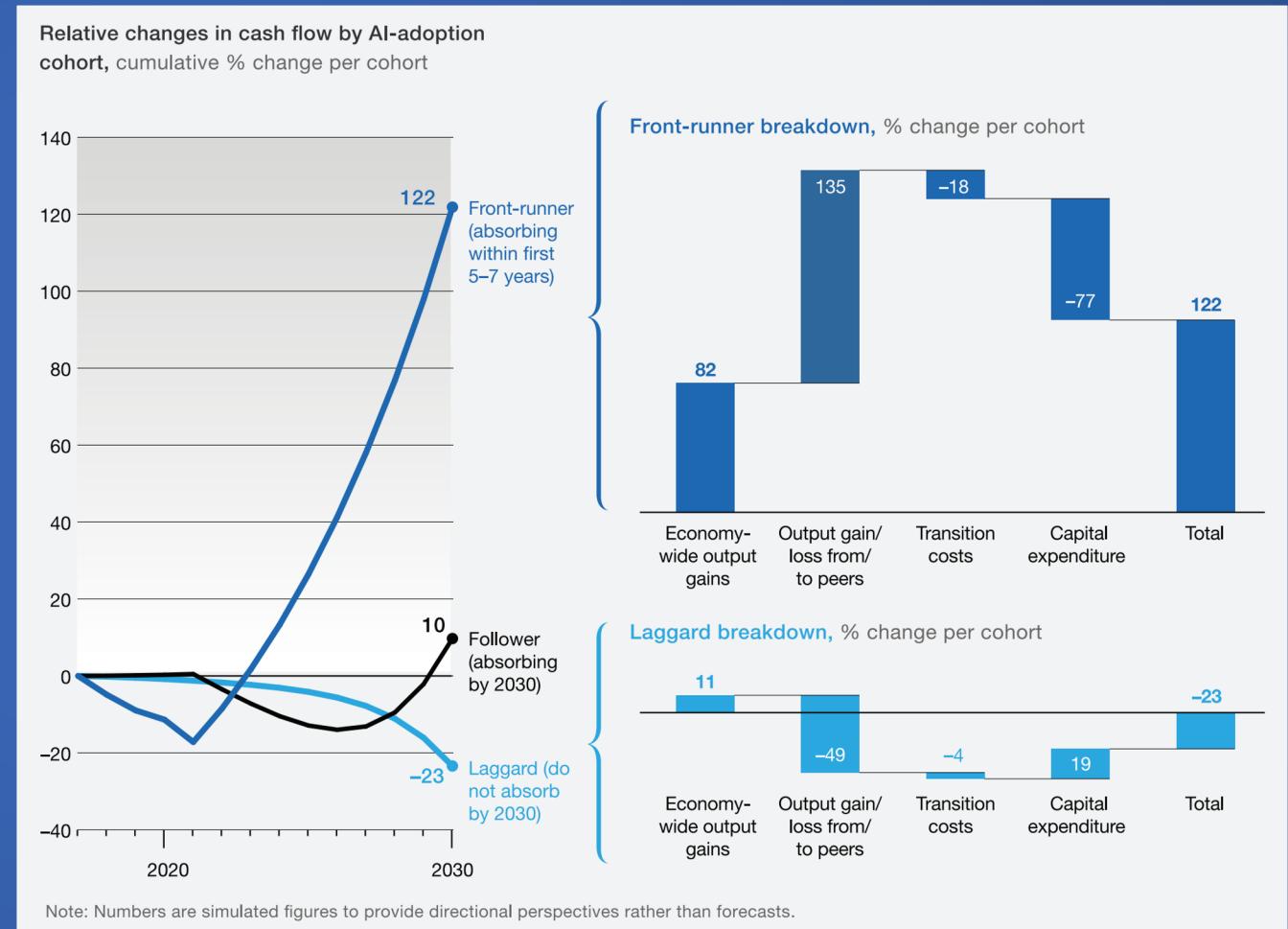
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# Why Industrial AI?

# Fast AI adoption creates **LARGER** economic gains

## - change in cash flow by 2030

- **front-runner** — +122%
- **follower** — +10 %
- **laggard** — -23%



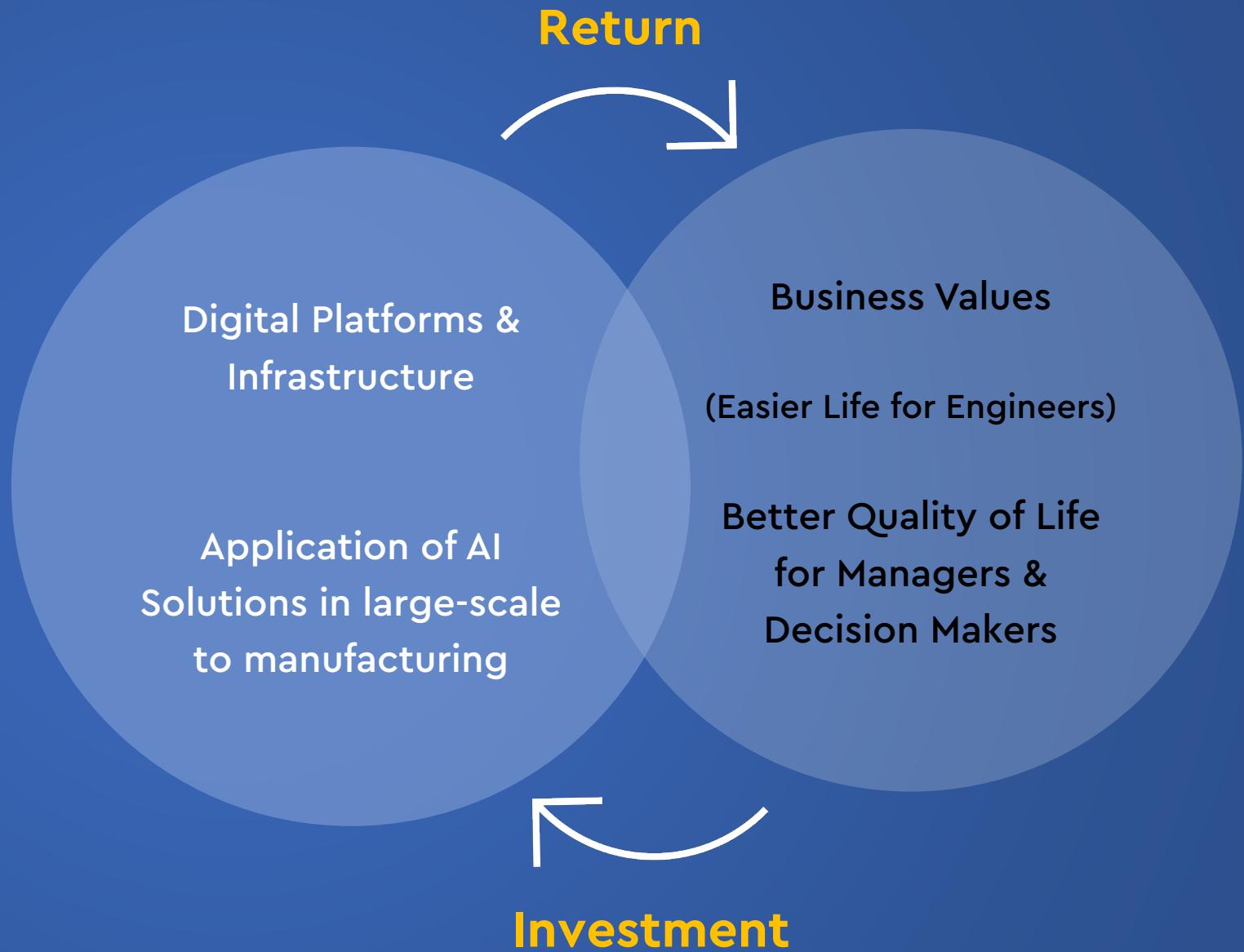
\* Source: McKinsey Global Institute Analysis (2019)

# Characteristics of Industrial AI

# Virtuous (or vicious) Cycle

## Data-centric AI

### Data Characteristics



"We need 1,000 models for 1,000 problems" – Andrew Ng

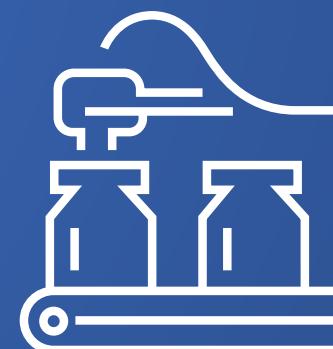
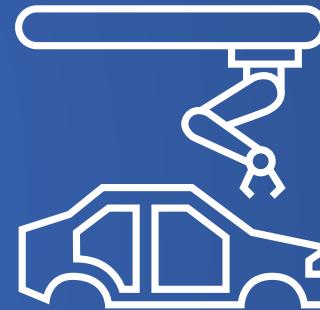
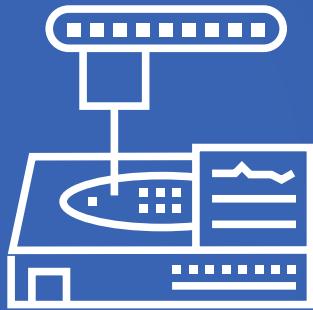
### Data-centric AI

Discipline of systematically engineering the data used to build an AI system

## Virtuous (or vicious) Cycle

### Data-centric AI

### Data Characteristics



Every company or sector has its own problems

## Virtuous (or vicious) Cycle

Data-centric AI

**Data Characteristics**



# **Opportunities vs Difficulties**

# Semiconductor is Great starting point for industrial AI

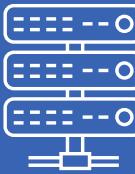


## Semiconductor Fab

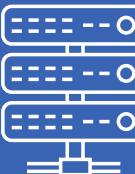
### Modern MEGA fab has

- ~1,000 process equipment
- ~100 metrology equipment
- ~1,000 wafers per day, per equipment
- ~1,000 processes per wafer
- 3-6-month cycle time

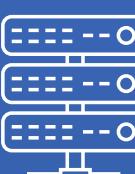
## Servers and Systems



**Equipment Sensor Data**  
(~1M parameters, ~1Tb/day)



**Metrology Image Data**  
(~1M images, ~10 Tb/day)



**Manufacturing Execution Data**  
(~10M events, ~10 Gb/day)

## Why Semiconductor?

Data availability from advanced digitalization

Diverse and sophisticated processes, ideal for expanding to new customers & sectors

Huge impact even within the sector itself

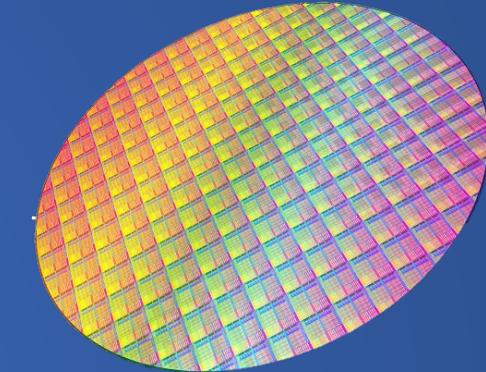
# Computer Vision in Manufacturing

# Computer vision and time-series ML in Manufacturing

## *Huge amount of image data to measure and inspect*

Scanning electron microscope (SEM) images, transmission electron microscope (TEM) images, etc.

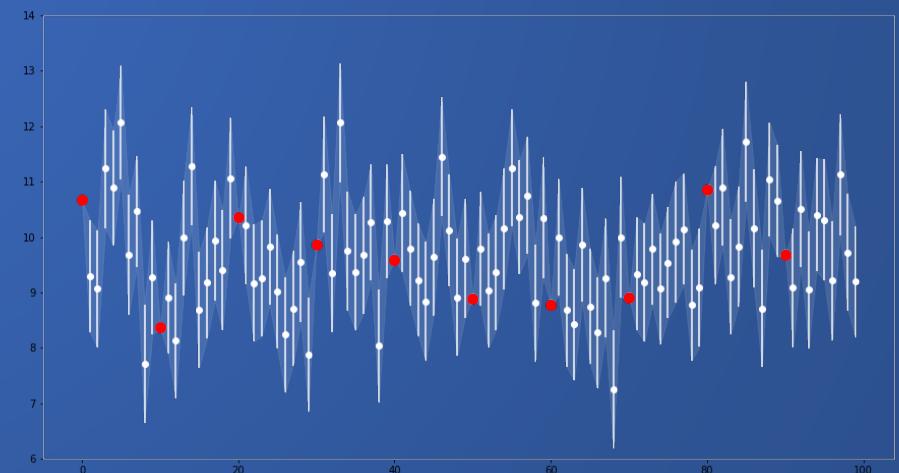
→ pattern classification, defect inspection, anomaly detection, etc.



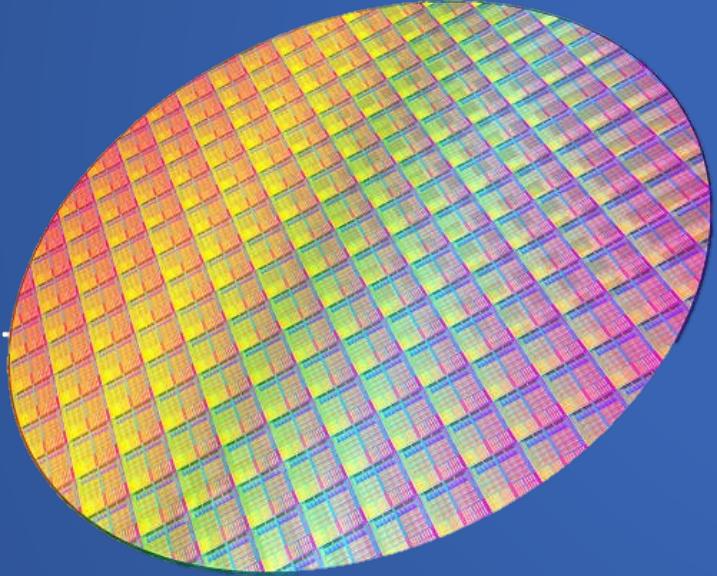
## *Almost all data coming from manufacturing - time-series data*

sensor data, process times, measurement, MES data

→ time-series ML – semi-supervised learning, (variational) Bayesian inference, anomaly detection



# Computer Vision ML for manufacturing



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## Metrology

*Measurement of critical features*

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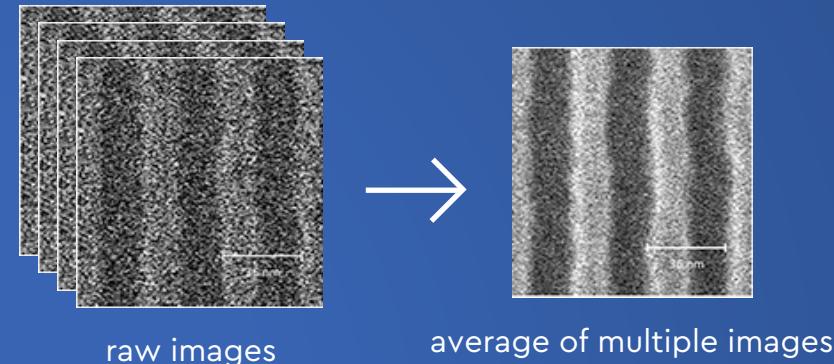
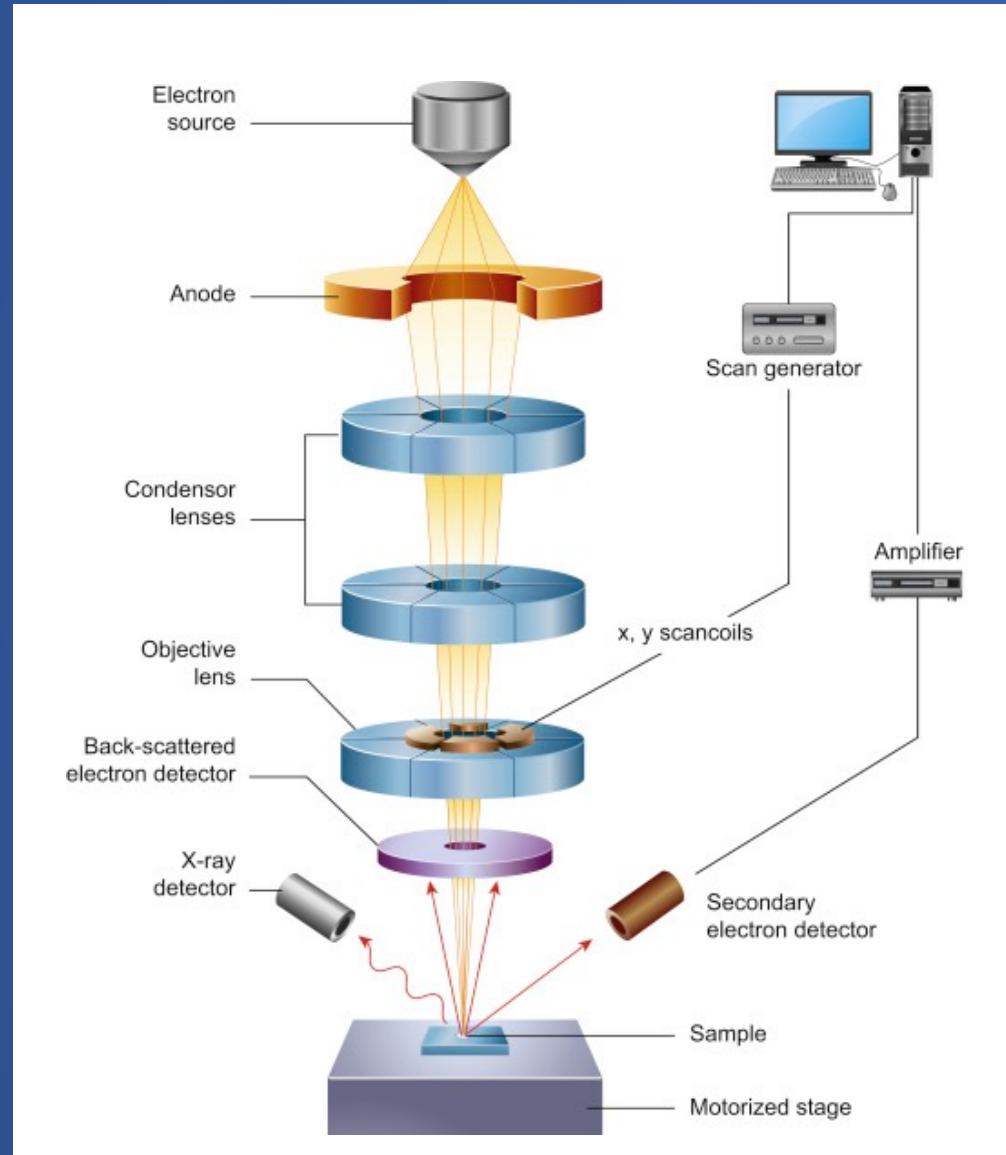
## Inspection

*Defect Inspection*

*Defect localization and classification*

Image courtesy of ASML

# Scanning Electron Microscope



# Image restoration

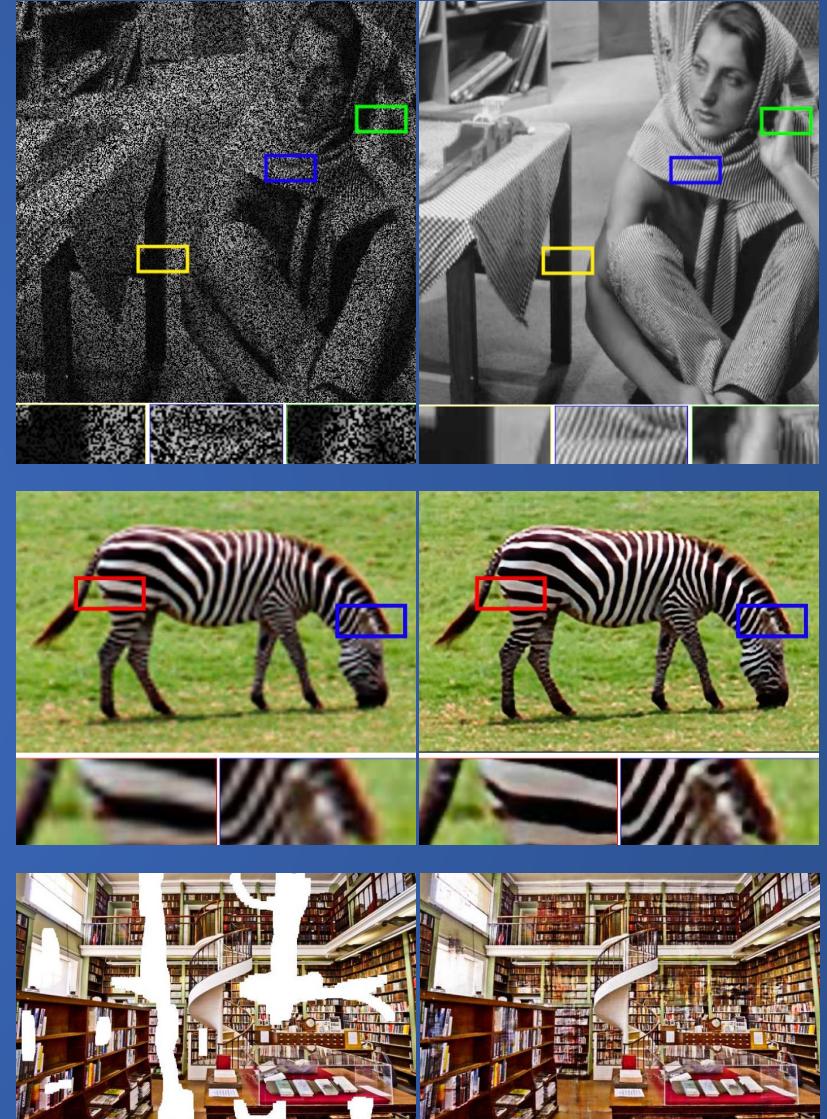
## Inverse problem of image corruption

$$x = f(y) + n$$

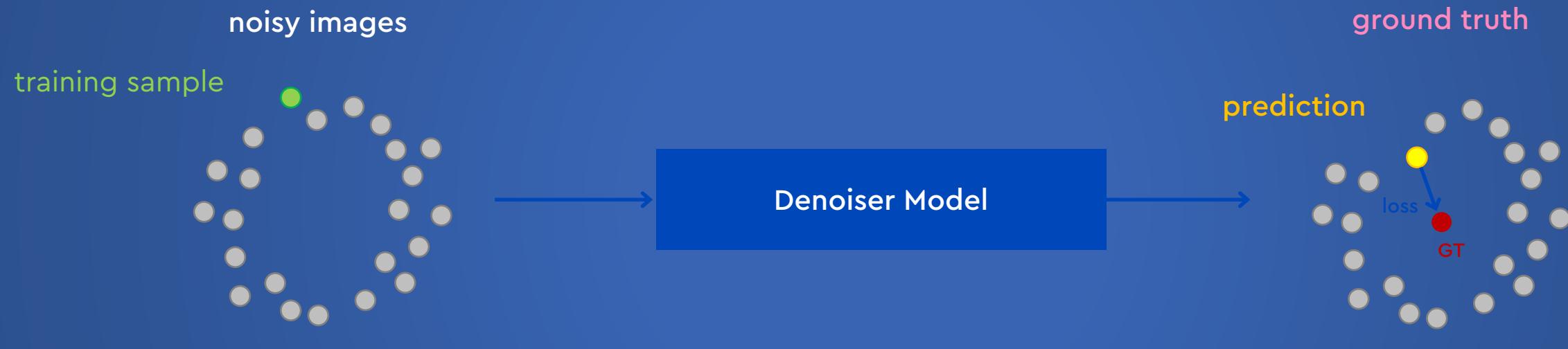
- y: clean image
- x: corrupted image
- n: noise

## $f(\cdot)$ & corresponding solutions

- Noising: Identity function → Denoising
- Downsampling → Super-resolution
- Missing pixels → Inpainting



# Supervised image denoising



*However, NOT possible to acquire ground-truth in practice.*

# Blind denoising without ground truth



*assuming mean of noise zero, averages of gradients, or equivalently, gradients of averages, surrogates for ground truth*

*Information containment perspective, noise generating filter does not erase perfectly ground truth!*

# Metrology based on segmentation and pattern recognition

Investment

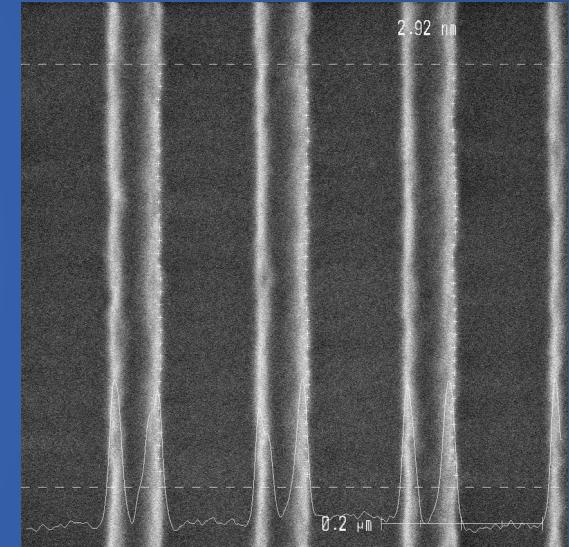
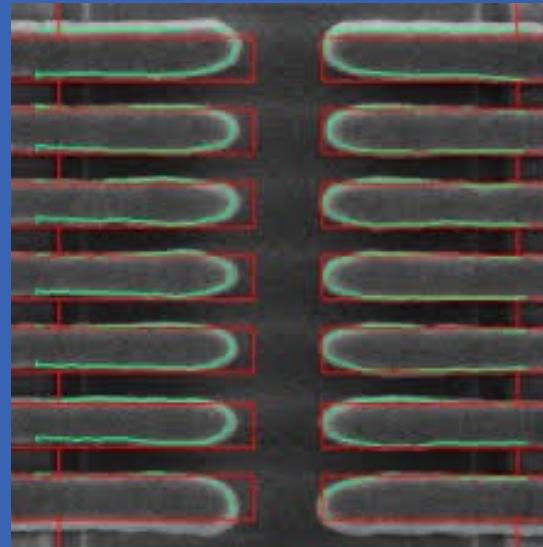
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Automatic measurement of critical dimensions

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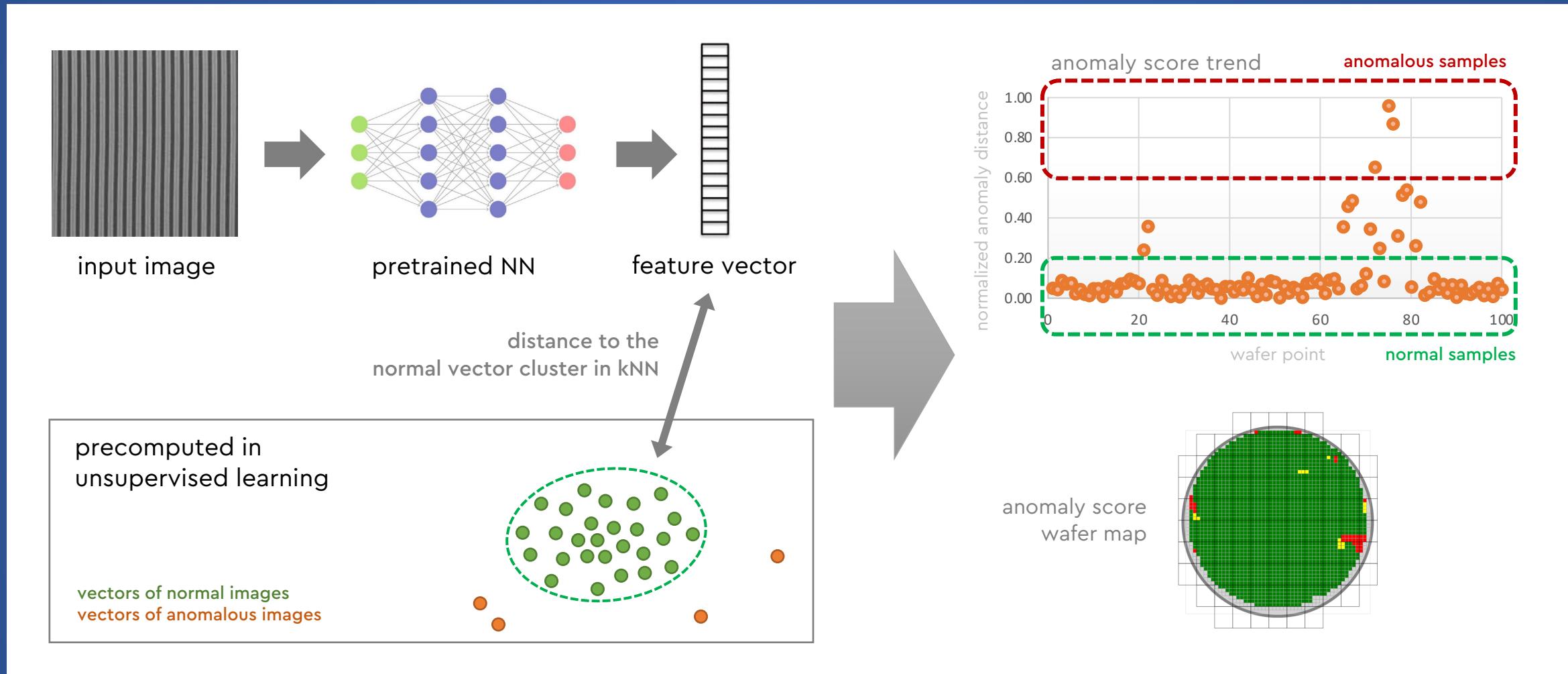
## Approaches

- Texture segmentation
- Repetitive pattern recognition
- Automatic measurement

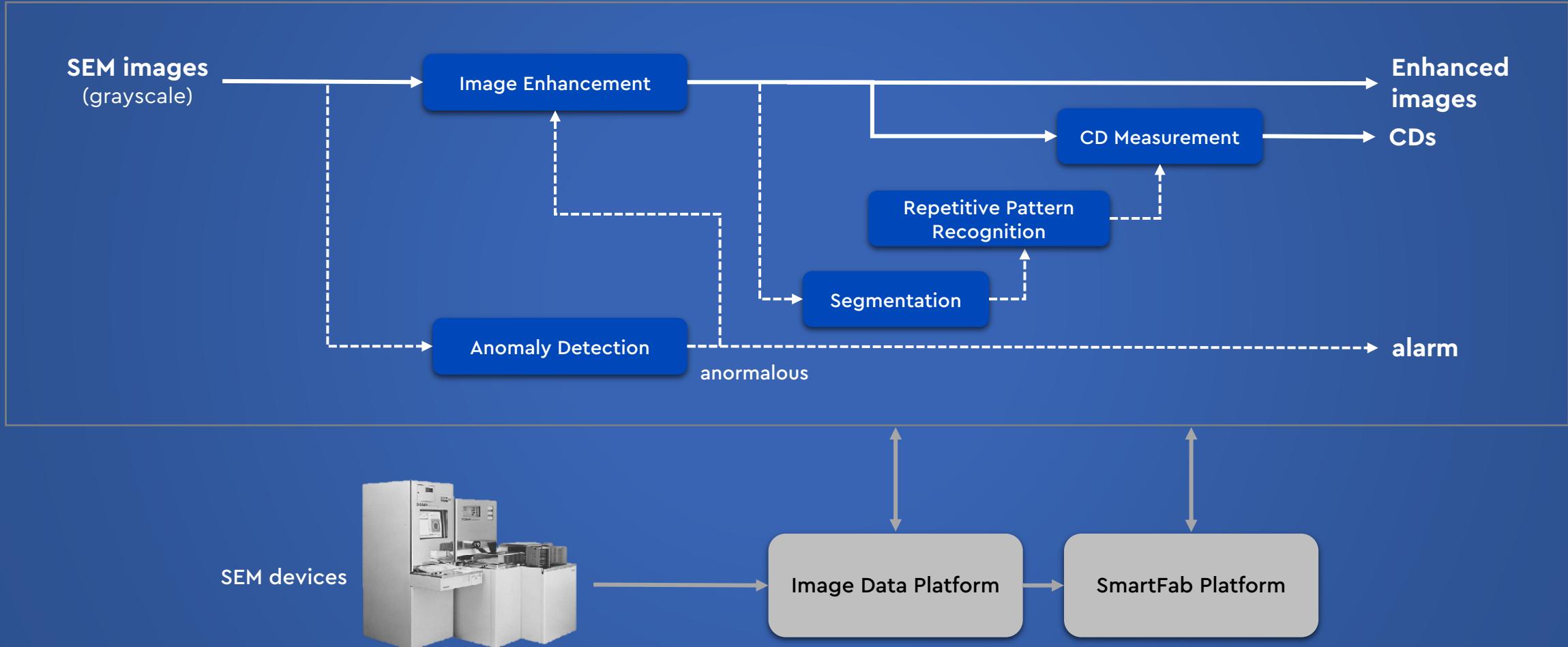


Extremely challenging!  
<0.1 nm measurement precision guaranteed

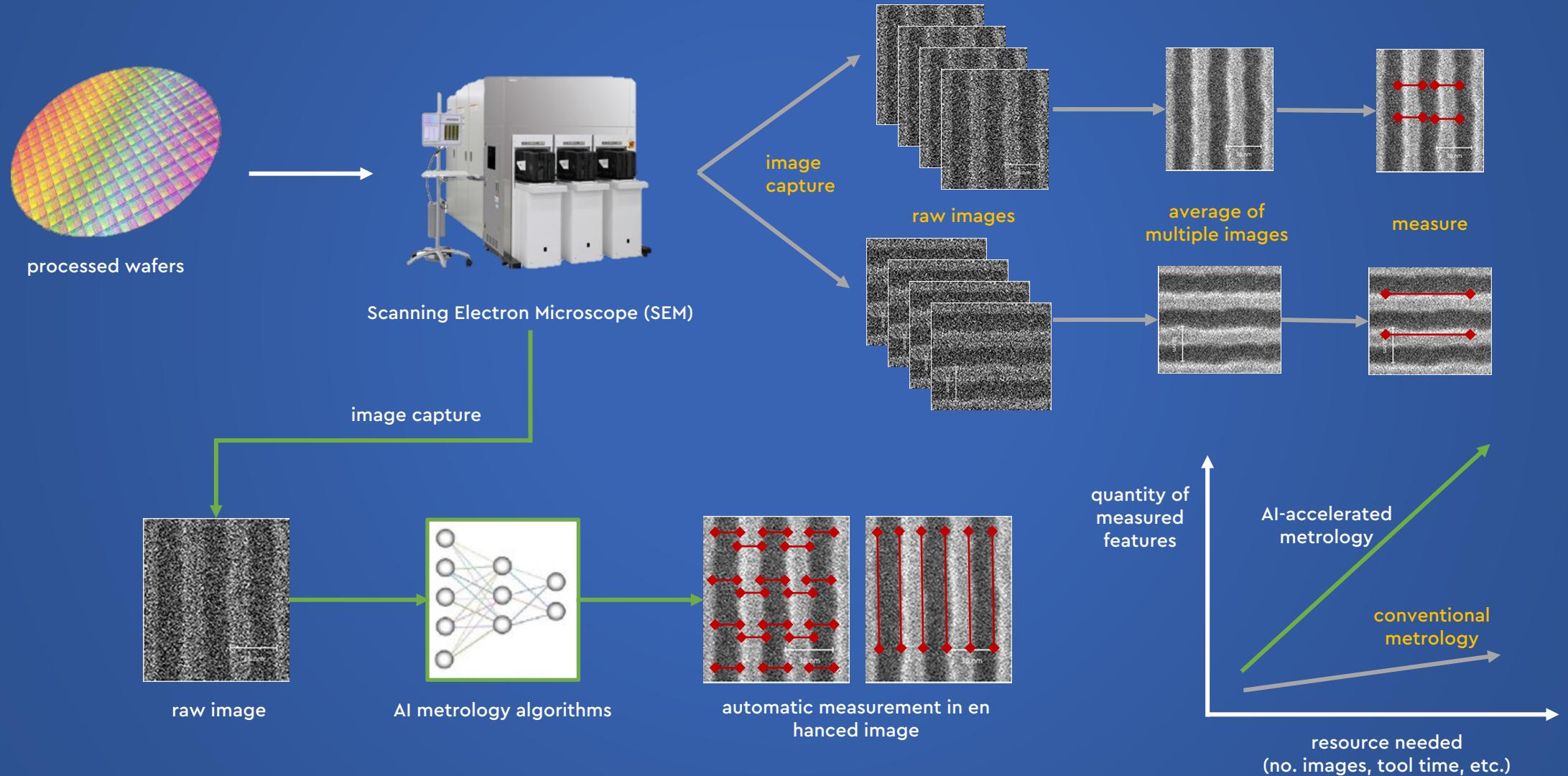
# Anomaly detection in unsupervised learning



# AI-accelerated metrology system



# Automatic measurement for semiconductor manufacturing

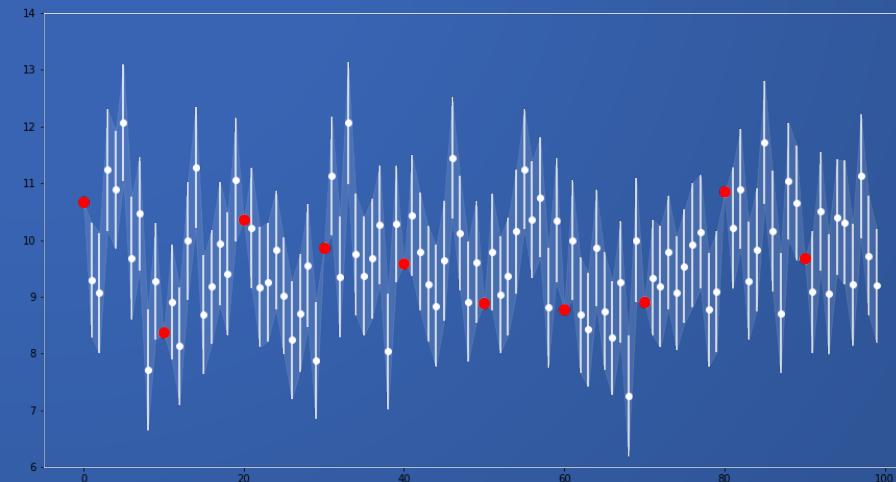
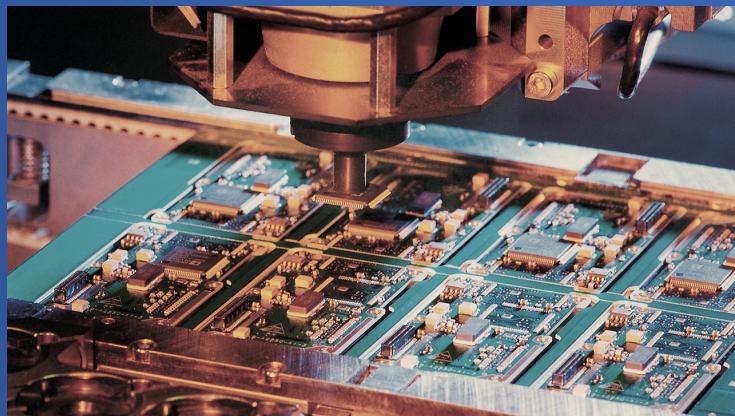


# Time-series ML

# Why time-series (TS) ML?

*manufacturing application is about one of the followings:*

- estimation of TS values - virtual metrology, yield prediction
- classification of TS values – predictive maintenance, recommendation system
- anomaly detection on TS - root cause analysis, root cause analysis for yield drop



# Difficulty & Advantage of TS ML

- *extremely difficult problems to solve*
- *not many researchers are interested*
  - *everyone's crazy about LLM, NLP & CV*
- *all academic papers deal with easy (or synthesized) data*
- *almost no definition can exist for time-series data*
- *NONE of algorithms in papers worked*
- *100% home-grown data & application-tailored algorithms required*

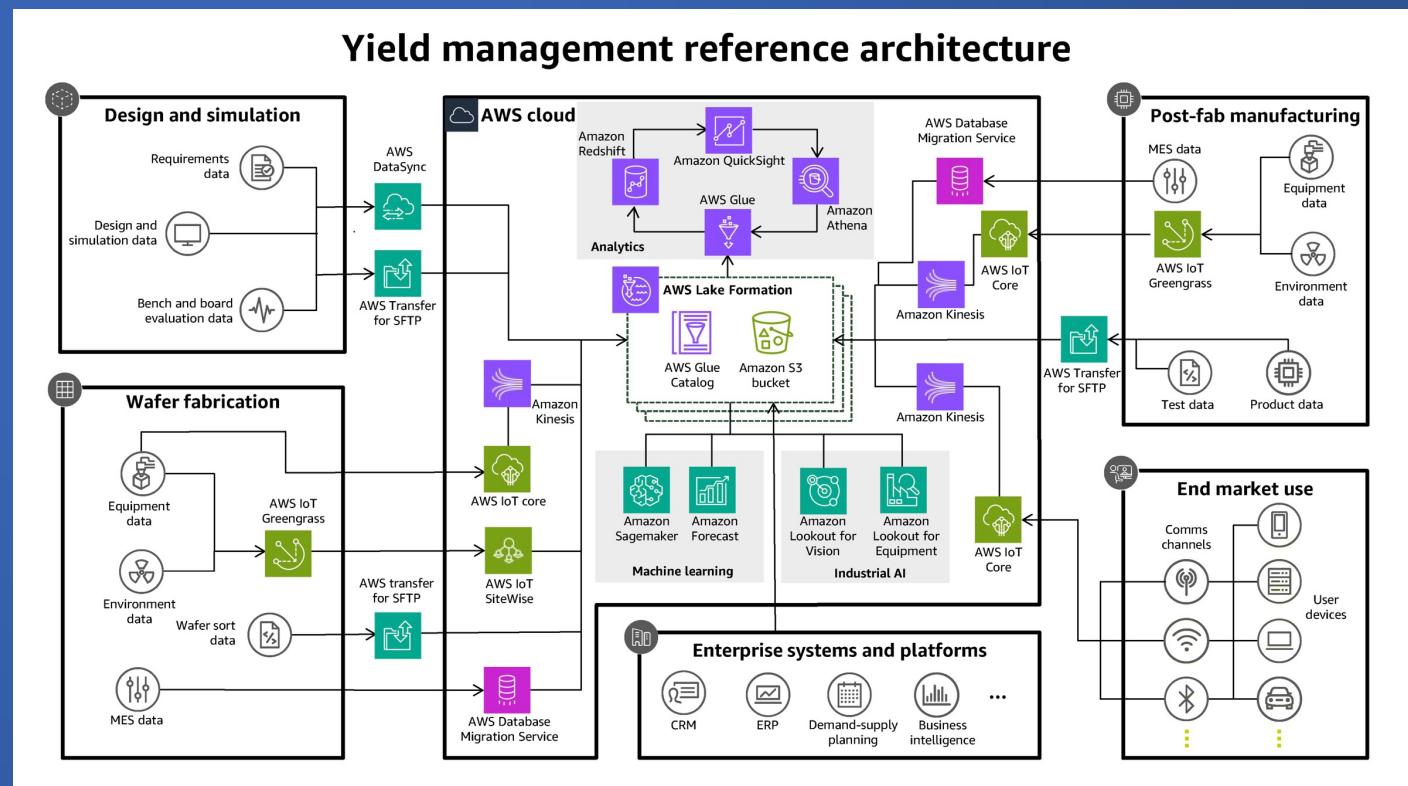
# TS prediction & estimation

- virtual metrology

- measure unmeasured processed materials using equipment sensor signals
- business impacts
  - investment on equipment, APC, SPC, yield improvement

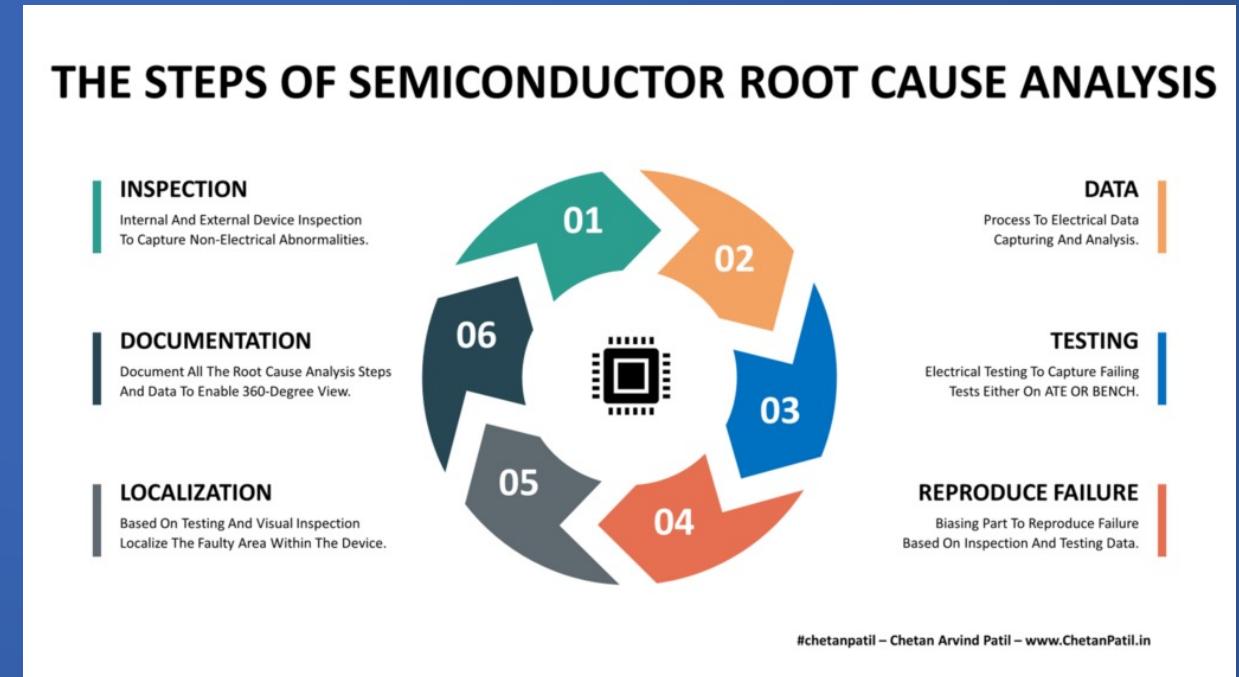
- yield prediction

- predict yield before final tests
- better product quality & profit



# Root cause analysis & recommendation system

- equipment alarm root cause analysis
  - when *alarm goes off*, find responsible equipment and root causes, where to look
  - reduce equipment downtime, make *process engineers' lives easier*
- recommendation system
  - when *things go wrong*, provide recommendation for finding root cause
  - recommendation steps to following based on *history data*



# Virtual Metrology

# What is VM?

*cannot measure all processed wafers*

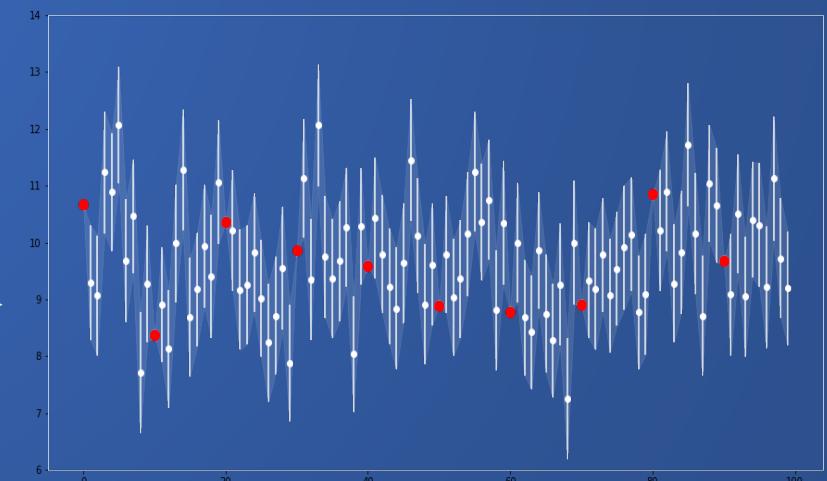
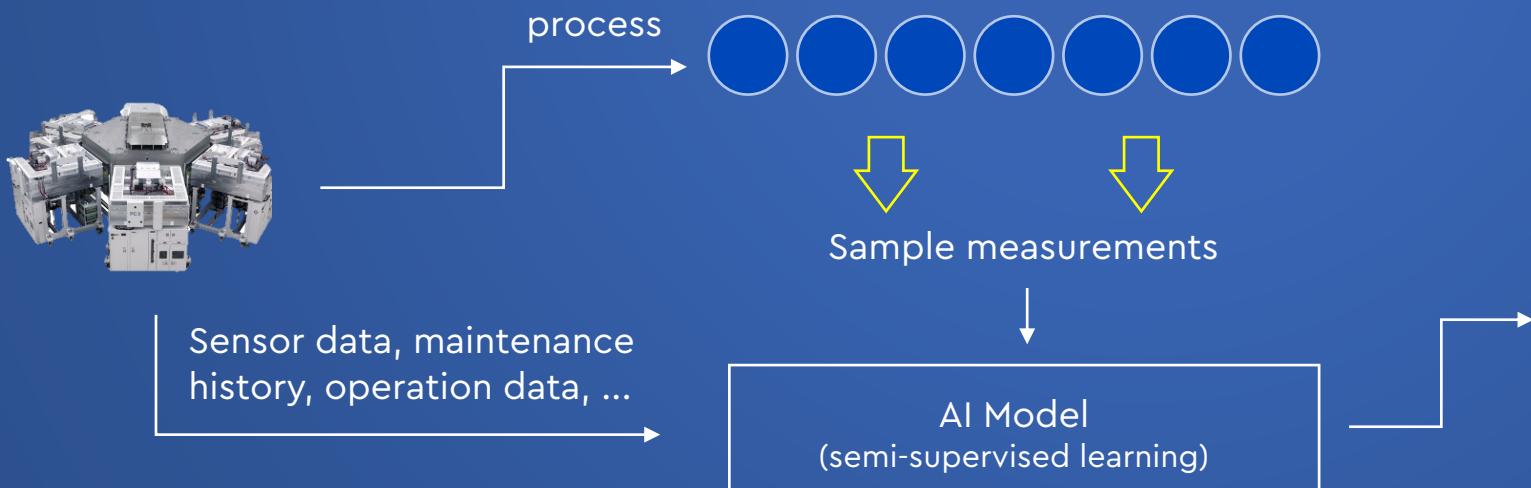
- measurement equipment too expensive
- full measuring hurts throughput
- Not enough space for all measurement equipment

*then what? do sampling (with very low sampling rate)*

- average sampling rate is less than 5%

**PROBLEM**

- predict the measurement of unmeasured material using indirect signals
- **measure without measuring**
- sensor data, maintenance history, operation data, . . .



# Data challenges

- covariate shift & concept drift

$\text{Prob}(x_{t_k}, x_{t_{k-1}}, x_{t_{k-2}}, \dots)$  changes over time

$\text{Prob}(y_{t_k} | y_{t_{k-1}}, y_{t_{k-2}}, \dots, x_{t_k}, x_{t_{k-1}}, x_{t_{k-2}}, \dots)$  changes over time

- fat data, *i.e.*, # features way larger than # data
- poor data quality; missing values, anomalies, wrong formats
- huge volume of data to process

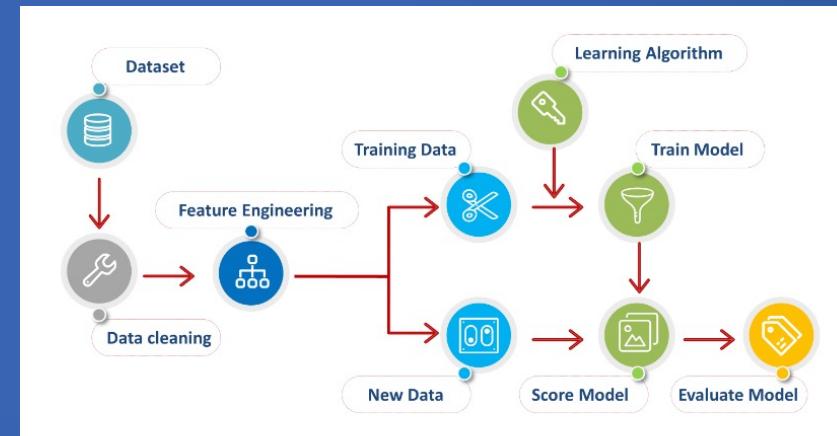
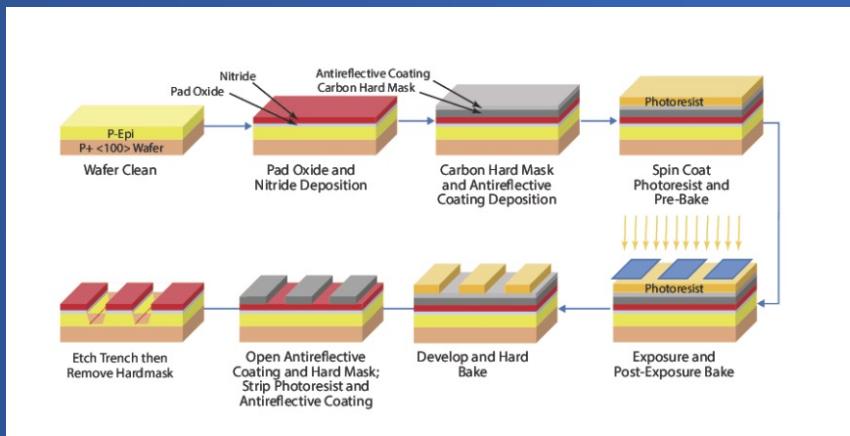
# Domain knowledge & fully home-grown models

*in most cases,  
domain knowledge is critical!*

close collaboration with customers required

*off-the-shelf algorithms  
not working!*

developing fully customized algorithms needed



# Business Impact made by VM

## *To the best of our knowledge*

- no organization has even been (*this*) successful with VM

## VM

- uses **home-grown AI model** to address with data drift/shift problems
- provide **credibility intervals** of predictions - reliability information

## *VM implications*

- virtually measuring **ALL wafers** – equivalent to investing on 100x measurement equipment
- enables optimal re-allocation of limited measurement resources

# **Speaker's Recommendations**

# Recommendations for Maximum Impact via Industrial AI

- Goal of projects
  - North star – Yield Improvement, Process Quality, Making Engr's lives easier
  - Hard problem – scheduling and optimization
- Be strategic!
  - Learn from others – lots of successes/failures of industrial AI
  - Ball park estimation for ROI – efforts, time, expertise, data
  - Reusability, common technology
  - Utilities vs technical excellency / uniqueness vs common technology
  - home-grown vs off-the-shelf

# Recommendations for Maximum Impact via Industrial AI

- Remember
  - data, data, data! – readiness, quality, procurement, pre-processing, DB
  - NEVER underestimate domain knowledge/expertise
    - data do **NOT** tell you everything
  - exploratory data analysis (EDA)
  - do NOT over-optimize your algorithms – ML is (almost) all about trials-&-errors
  - overfitting/generalization/concept drift/shift - way more important than you could ever imagine
  - DevOps, MLOps, Agile dev, software development/engineering

**Thank You**